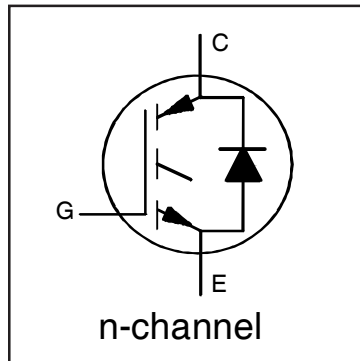


**INSULATED GATE BIPOLAR TRANSISTOR WITH
 ULTRAFAST SOFT RECOVERY DIODE**

Features

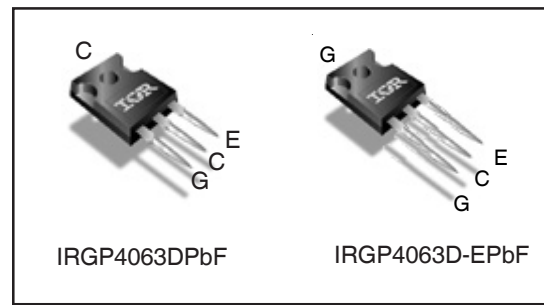
- Low $V_{CE(ON)}$ Trench IGBT Technology
- Low switching losses
- Maximum Junction temperature 175 °C
- 5 μ S short circuit SOA
- Square RBSOA
- 100% of the parts tested for 4X rated current (I_{LM})
- Positive $V_{CE(ON)}$ Temperature co-efficient
- Ultra fast soft Recovery Co-Pak Diode
- Tight parameter distribution
- Lead Free Package



$V_{CES} = 600V$
$I_C = 48A, T_C = 100^\circ C$
$t_{SC} \geq 5\mu s, T_{J(max)} = 175^\circ C$
$V_{CE(on)} \text{ typ.} = 1.65V$

Benefits

- High Efficiency in a wide range of applications
- Suitable for a wide range of switching frequencies due to Low $V_{CE(ON)}$ and Low Switching losses
- Rugged transient Performance for increased reliability
- Excellent Current sharing in parallel operation
- Low EMI



G	C	E
Gate	Collector	Emitter

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	96	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	48	
I_{CM}	Pulse Collector Current	200	
I_{LM}	Clamped Inductive Load Current ①	192	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	96	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	48	
I_{FM}	Diode Maximum Forward Current ③	192	
V_{GE}	Continuous Gate-to-Emitter Voltage	± 20	V
	Transient Gate-to-Emitter Voltage	± 30	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	330	W
	$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1 N·m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance Junction-to-Case-(each IGBT)	—	—	0.45	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance Junction-to-Case-(each Diode)	—	—	0.92	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface)	—	0.24	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (typical socket mount)	—	—	40	

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig
V _{(BR)CES}	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V _{GE} = 0V, I _C = 150μA ④	CT6
ΔV _{(BR)CES} /ΔT _J	Temperature Coeff. of Breakdown Voltage	—	0.30	—	V/°C	V _{GE} = 0V, I _C = 1mA (25°C-175°C)	CT6
V _{CE(on)}	Collector-to-Emitter Saturation Voltage	—	1.65	2.14	V	I _C = 48A, V _{GE} = 15V, T _J = 25°C	5,6,7
		—	2.0	—		I _C = 48A, V _{GE} = 15V, T _J = 150°C	9,10,11
		—	2.05	—		I _C = 48A, V _{GE} = 15V, T _J = 175°C	
V _{GE(th)}	Gate Threshold Voltage	4.0	—	6.5	V	V _{CE} = V _{GE} , I _C = 1.4mA	9, 10,
ΔV _{GE(th)} /ΔT _J	Threshold Voltage temp. coefficient	—	-21	—	mV/°C	V _{CE} = V _{GE} , I _C = 1.0mA (25°C - 175°C)	11, 12
g _{fe}	Forward Transconductance	—	32	—	S	V _{CE} = 50V, I _C = 48A, PW = 80μs	
I _{CES}	Collector-to-Emitter Leakage Current	—	1.0	150	μA	V _{GE} = 0V, V _{CE} = 600V	
		—	450	1000		V _{GE} = 0V, V _{CE} = 600V, T _J = 175°C	
V _{FM}	Diode Forward Voltage Drop	—	1.95	2.91	V	I _F = 48A	8
		—	1.45	—		I _F = 48A, T _J = 175°C	
I _{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V _{GE} = ±20V	

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig
Q _g	Total Gate Charge (turn-on)	—	95	140	nC	I _C = 48A	24
Q _{ge}	Gate-to-Emitter Charge (turn-on)	—	28	42		V _{GE} = 15V	CT1
Q _{gc}	Gate-to-Collector Charge (turn-on)	—	35	53		V _{CC} = 400V	
E _{on}	Turn-On Switching Loss	—	625	1141	μJ	I _C = 48A, V _{CC} = 400V, V _{GE} = 15V	CT4
E _{off}	Turn-Off Switching Loss	—	1275	1481		R _G = 10Ω, L = 200μH, L _S = 150nH, T _J = 25°C	
E _{total}	Total Switching Loss	—	1900	2622		Energy losses include tail & diode reverse recovery	
t _{d(on)}	Turn-On delay time	—	60	78	ns	I _C = 48A, V _{CC} = 400V, V _{GE} = 15V	CT4
t _r	Rise time	—	40	56		R _G = 10Ω, L = 200μH, L _S = 150nH, T _J = 25°C	
t _{d(off)}	Turn-Off delay time	—	145	176			
t _f	Fall time	—	35	46			
E _{on}	Turn-On Switching Loss	—	1625	—	μJ	I _C = 48A, V _{CC} = 400V, V _{GE} = 15V	13, 15
E _{off}	Turn-Off Switching Loss	—	1585	—		R _G = 10Ω, L = 200μH, L _S = 150nH, T _J = 175°C ④	CT4
E _{total}	Total Switching Loss	—	3210	—		Energy losses include tail & diode reverse recovery	WF1, WF2
t _{d(on)}	Turn-On delay time	—	55	—	ns	I _C = 48A, V _{CC} = 400V, V _{GE} = 15V	14, 16
t _r	Rise time	—	45	—		R _G = 10Ω, L = 200μH, L _S = 150nH	CT4
t _{d(off)}	Turn-Off delay time	—	165	—		T _J = 175°C	WF1
t _f	Fall time	—	45	—			WF2
C _{ies}	Input Capacitance	—	3025	—	pF	V _{GE} = 0V	23
C _{oes}	Output Capacitance	—	245	—		V _{CC} = 30V	
C _{res}	Reverse Transfer Capacitance	—	90	—		f = 1.0Mhz	
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T _J = 175°C, I _C = 192A V _{CC} = 480V, V _p = 600V R _G = 10Ω, V _{GE} = +15V to 0V	4 CT2
SCSOA	Short Circuit Safe Operating Area	5	—	—	μs	V _{CC} = 400V, V _p = 600V R _G = 10Ω, V _{GE} = +15V to 0V	22, CT3 WF4
E _{rec}	Reverse Recovery Energy of the Diode	—	845	—	μJ	T _J = 175°C	17, 18, 19
t _{rr}	Diode Reverse Recovery Time	—	115	—	ns	V _{CC} = 400V, I _F = 48A	20, 21
I _{rr}	Peak Reverse Recovery Current	—	40	—	A	V _{GE} = 15V, R _G = 10Ω, L = 200μH, L _S = 150nH	WF3

Notes:

- ① V_{CC} = 80% (V_{CES}), V_{GE} = 20V, L = 200μH, R_G = 10Ω.
- ② This is only applied to TO-247AC package.
- ③ Pulse width limited by max. junction temperature.
- ④ Refer to AN-1086 for guidelines for measuring V_{(BR)CES} safely.